



BAP64-03

Silicon PIN diode

Rev. 7 — 28 April 2014

Product data sheet

1. Product profile

1.1 General description

Planar PIN diode in a SOD323 very small plastic SMD package.

1.2 Features and benefits

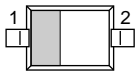

- High voltage, current controlled
- RF resistor for RF attenuators and switches
- Low diode capacitance
- Low diode forward resistance
- Low series inductance
- For applications up to 3 GHz

1.3 Applications

- RF attenuators and switches

2. Pinning information

Table 1. Discrete pinning

Pin	Description	Simplified outline	Symbol
1	cathode ^[1]		 <i>sym006</i>
2	anode		

[1] The marking bar indicates the cathode.

3. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
BAP64-03	-	plastic surface mounted package; 2 leads;	SOD323



4. Marking

Table 3. Marking

Type number	Marking code
BAP64-03	A3

5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	175	V
I_F	forward current		-	100	mA
P_{tot}	total power dissipation	$T_{sp} = 90\text{ °C}$	-	500	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-65	+150	°C

6. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		120	K/W

7. Characteristics

Table 6. Characteristics

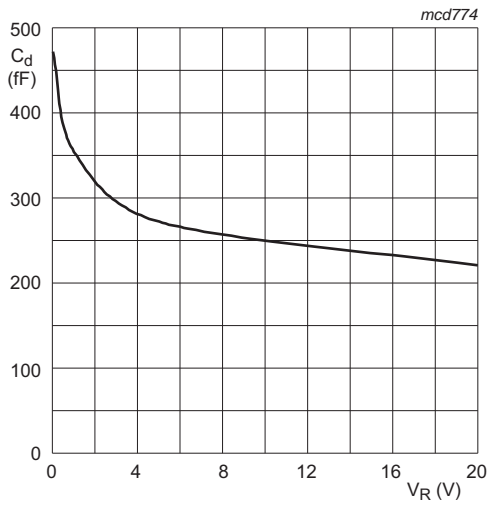
$T_j = 25\text{ °C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage	$I_F = 50\text{ mA}$	-	0.95	1.1	V
I_R	reverse current	$V_R = 175\text{ V}$	-	-	10	μA
		$V_R = 20\text{ V}$	-	-	1	μA
C_d	diode capacitance	see Figure 1 ; $f = 1\text{ MHz}$;				
		$V_R = 0\text{ V}$	-	0.48	-	pF
		$V_R = 1\text{ V}$	-	0.35	-	pF
		$V_R = 20\text{ V}$	-	0.23	0.35	pF

Table 6. Characteristics ...continued $T_j = 25\text{ °C}$ unless otherwise specified.

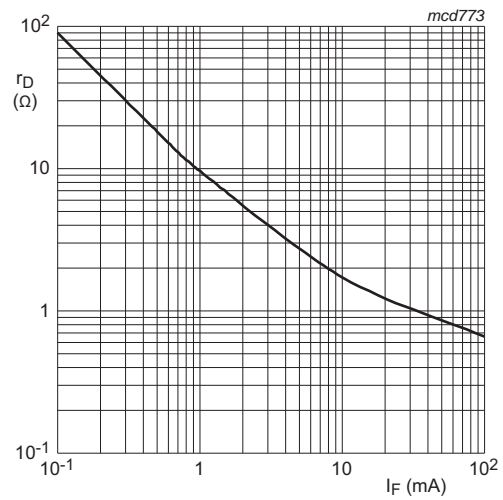
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
r_D	diode forward resistance	see Figure 2 ; $f = 100\text{ MHz}$; [1]				
		$I_F = 0.5\text{ mA}$	-	20	40	Ω
		$I_F = 1\text{ mA}$	-	10	20	Ω
		$I_F = 10\text{ mA}$	-	2.0	3.8	Ω
		$I_F = 100\text{ mA}$	-	0.7	1.35	Ω
τ_L	charge carrier life time	when switched from $I_F = 10\text{ mA}$ to $I_R = 6\text{ mA}$; $R_L = 100\ \Omega$; measured at $I_R = 3\text{ mA}$	-	1.55	-	μs
L_S	series inductance		-	1.68	-	nH

[1] Guaranteed on AQL basis: inspection level S4, AQL 1.0.



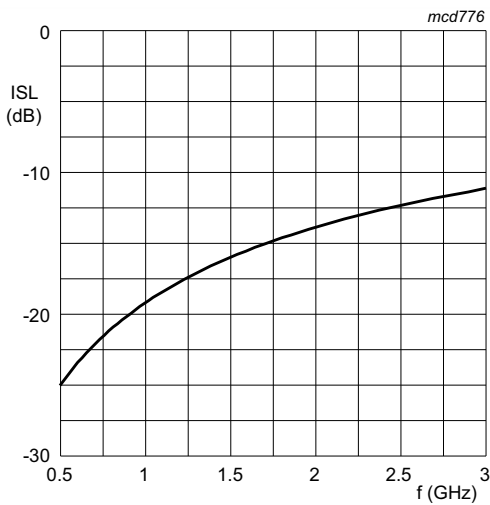
$f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}.$

Fig 1. Diode capacitance as a function of reverse voltage; typical values



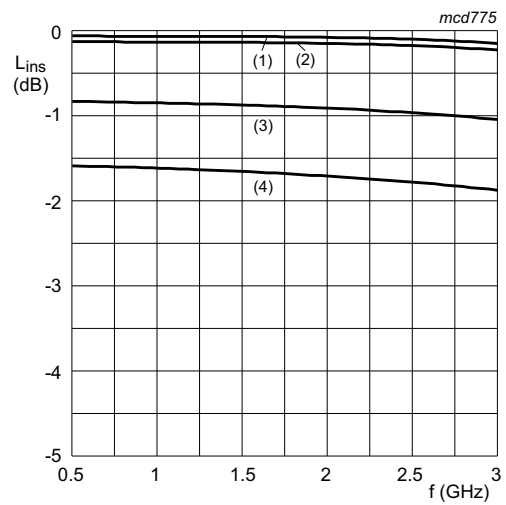
$f = 100 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}.$

Fig 2. Forward resistance as a function of forward current; typical values



$T_{\text{amb}} = 25 \text{ }^\circ\text{C}$
Diode zero biased and inserted in series with a 50 Ω stripline circuit

Fig 3. Isolation of the diode as a function of frequency; typical values



$T_{\text{amb}} = 25 \text{ }^\circ\text{C}$
(1) $I_F = 100 \text{ mA}$
(2) $I_F = 10 \text{ mA}$
(3) $I_F = 1 \text{ mA}$
(4) $I_F = 0.5 \text{ mA}$
Diode inserted in series with a 50 Ω stripline circuit and biased via the analyzer Tee network

Fig 4. Insertion loss of the diode as a function of frequency; typical values

8. Package outline

Plastic surface-mounted package; 2 leads

SOD323

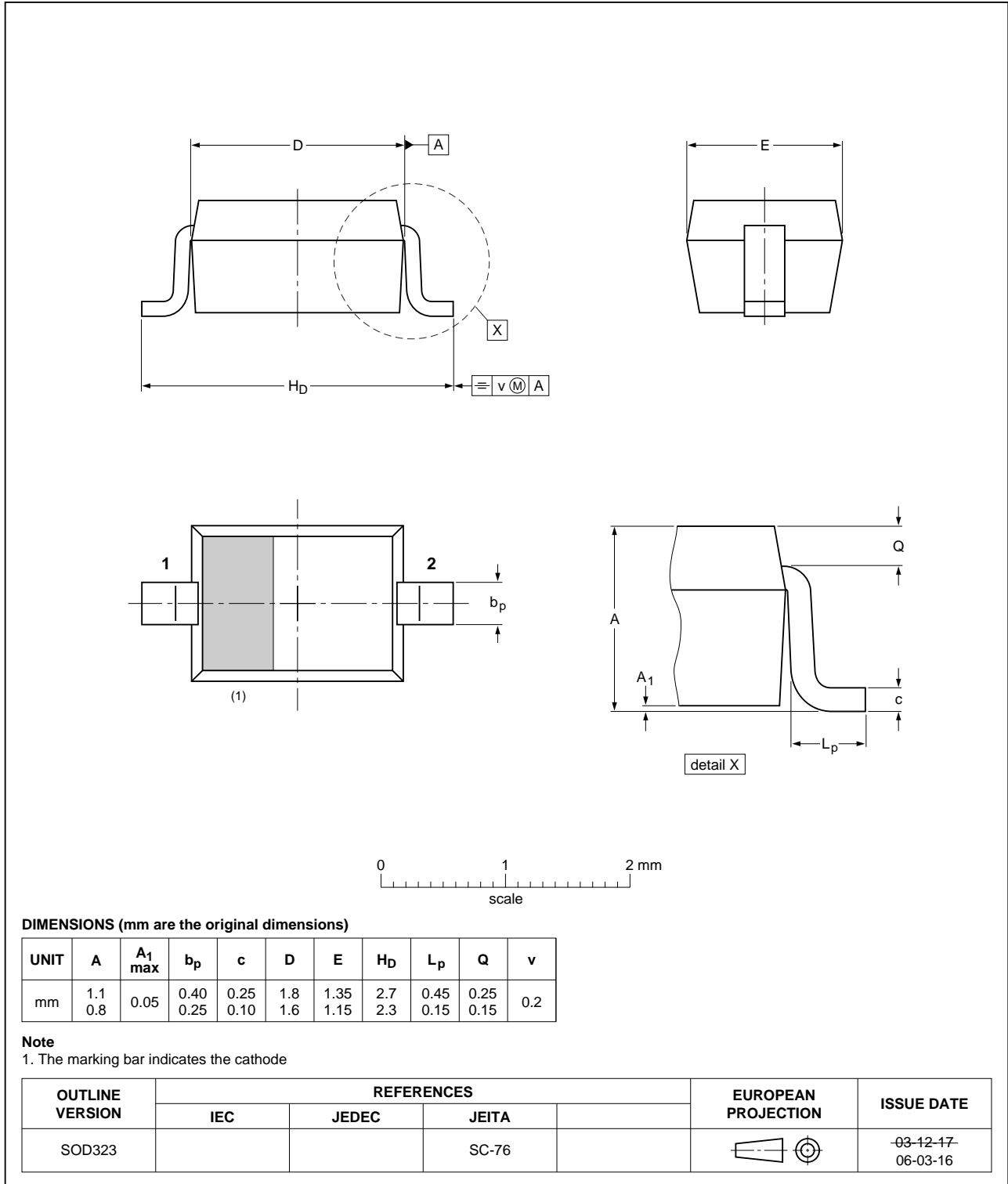


Fig 5. Package outline SOD323

9. Abbreviations

Table 7. Abbreviations

Acronym	Description
PIN	P-type, Intrinsic, N-type
SMD	Surface Mounted Device
RF	Radio Frequency

10. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP64-03 v.7	20140428	Product data sheet	-	BAP64-03 v.6
Modifications:	<ul style="list-style-type: none"> Rollback to previous version 			
BAP64-03 v.6	20140211	Product data sheet	-	BAP64-03 v.5
BAP64-03 v.5 (9397 750 12632)	20040211	Product specification	-	BAP64-03 v.4
BAP64-03 v.4 (9397 750 06279)	19990827	Product specification	-	BAP64-03_N v.3
BAP64-03_N v.3 (9397 750 06087)	19990616	Preliminary specification	-	BAP64-03 v.2
BAP64-03 v.2 (9397 750 05557)	19990510	Objective specification	-	BAP64-03_N v.1
BAP64-03_N v.1 (9397 750 05493)	19981204	Objective specification	-	-

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11.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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